MI0805K110R-10

UNCONTROLLED **DOCUMENT**

PHYSICAL DIMENSIONS:

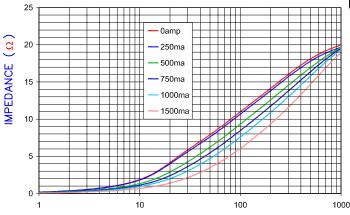
A 2.00 [.079] ± 0.20 [.008]

B 1.25 [.049] ± 0.20 [.008]

± 0.20 [.008] 0.90 [.035]

0.51 [.020] ± 0.25 [.010]

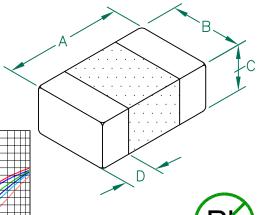
Z vs FREQUENCY IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

|Z| , R, AND X vs. FREQUENCY

FREQUENCY (MHz)



ELECTRICAL CHARACTERISTICS:						
Z @ 100MHz (Ω)		DCR (Ω)	Rated Current			
Nominal	11					
Minimum	8					
Maximum	14	0.06	1500 mA			

NOTES: UNLESS OTHERWISE SPECIFIED

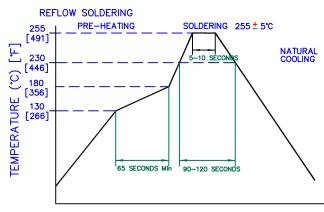
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING

0.66 .026 1.47 [.058]3.23 $\lceil .127 \rceil$

(For Ī.03

RECOMMENDED SOLDERING CONDITIONS



E D D C C B		
/95/EC C		
D 95/EC	2	Ε
/95/EC <u>с</u> в		D
В	/95/EC	C
		В

	ave soldering, add 0.762 to this dimension)			
	DIMENSIONS ARE IN mm [INCH	ES].		This print is the property of Laird
				Tech, and is loaned in confidence subject to return upon request ar
				with the understanding that no
				copies shall be made without the
				written consent of Laird Tech. All rights to design or invention are
Е	ADD OPERATING TEMPERATURE	08/05/13	3 QU	reserved.
_	UPDATE LAIRD LOGO AND REFLOW CURVE	TE LAIRD LOGO AND REFLOW CURVE		PROJECT/PART NUMBER:
D	CHANGE TO PAPER TAPE	03/04/10	JUN	MI0805K110R-10
O	UPDATE COMPANY LOGO	08/06/08	JRK	WIIOOOSKITOK TO
æ	ADD ROHS & UPDATE COMPANY LOGO	08/28/07	JRK	DATE: 04/05/04 SC
Α	ORIGINAL DRAFT	04/05/04	ТМВ	100 4
RFV	DESCRIPTION	DATE	INT	" MI0805K110R-10-E

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CO-FIRE

AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3227

(C)

MPEDANCE